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	Filing Date		2001-08-13
	First Named Inventor	QUAN, SON KY	
	Art Unit	2831	
	Examiner Name	NGO, HUNG V.	
	Attorney Docket Number	SC09785T-CD1	

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38	Nanya, website, http://www.nanyapcb.com.tw/nypcb/english/index.aspx	<input type="checkbox"/>
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